

**AMENDMENTS TO THE CLAIMS:**

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

**LISTING OF CLAIMS:**

1. (Original) An electronic device comprising an IC element, and a first circuit layer and a second circuit layer,

wherein the IC element further provides a base substrate formed of silicon, a semiconductor circuit layer forming a semiconductor circuit on one side of the base substrate, and an electrode formed on the semiconductor circuit layer,

and wherein the first circuit layer is electrically connected either to the other side of the base substrate or the electrode and the second circuit layer is electrically connected to that same other side of the base substrate or the electrode, whichever remains unconnected.

2. (Original) The electronic device according to claim 1 wherein the other side of the base substrate is connected with either the first or the second circuit layer via a conductive adhesive agent.

3. (Original) The electronic device according to claim 2 wherein the conductive adhesive agent is comprised of a thermal hardenable matrix resin, and metallic pieces of granular form, scalelike form or acicular form.

4. (Original) The electronic device according to claim 1 wherein at least the other side of the base substrate is connected with either the first or the second circuit layer via an anisotropic conductive adhesive layer.

5. (Original) The electronic device according to claim 4 wherein the anisotropic conductive adhesive layer includes a matrix resin and conductive particles comprised of either metallic particles or organic resinous particles having a metallic layer formed on the surface thereof.

6. (Currently amended) The electronic device according to ~~either of claim 4 or claim 5~~ wherein the IC element is sealed by a matrix resin of anisotropic conductive adhesive agent.

7. (Currently amended) The electronic device according to claim 1 ~~any of claims 1 to claim 6~~ wherein at least either the first or the second circuit layers includes a conductive layer of aluminum or copper.

8. (Currently amended) The electronic device according to claim 1 ~~any of claims 1 to claim 7~~ wherein at least either the first or the second circuit layers is supported on a base substrate comprised of an organic resin, this organic resin being ~~selected~~selectable from the group consisting of polyvinyl chloride (PVC), acrylonitrile butadiene styrene (ABS), polyethylene terephthalate (PET), polyethylene terephthalate glycol (PETG), polyethylene naphthalate (PEN), polycarbonate resin (PC), by axial polyester (O-PET), or polyimide resin.

9. (Currently amended) The electronic device according to claim 1 ~~any of claims 1 to claim 7~~ wherein at least either the first or the second circuit layers is supported on a base substrate comprised of paper.

10. (New) The electronic device according to claim 5 wherein the IC element is sealed by a matrix resin of anisotropic conductive adhesive agent.

11. (New) The electronic device according to claim 10 wherein at least either the first or the second circuit layers includes a conductive layer of aluminum or copper.

12. (New) The electronic device according to claim 11 wherein at least either the first or the second circuit layers is supported on a base substrate comprised of an organic resin, this organic resin being selected from the group consisting of polyvinyl chloride (PVC), acrylonitrile butadiene styrene (ABS), polyethylene terephthalate (PET), polyethylene terephthalate glycol (PETG), polyethylene naphthalate (PEN), polycarbonate resin (PC), by axial polyester (O-PET), or polyimide resin.

13. (New) The electronic device according to claim 12 wherein at least either the first or the second circuit layers is supported on a base substrate comprised of paper.